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SCHS368A-OCTOBER 2008-REVISED DECEMBER 2008

RAD-TOLERANT CLASS V, QUADRUPLE 2-INPUT POSITIVE-NOR GATES

FE	LATURES	LOB	V PACKAGE
٠	AC Types Feature 1.5-V to 5.5-V Operation		P VIEW)
٠	Rad-Tolerant: 50 KRad(Si) TID (1)		
	 TID Dose Rate < 2 mRad/sec 		
•	QML-V Qualified, SMD 5962-87612	1A [] 2	13 4Y
		1B 🛛 3	12 🛛 4B
		2Y 🛛 4	11 🛛 4A
		2A 🛛 5	10 🛛 3Y
(1)	Radiation tolerance is a typical value based upon initial device	2B 🛛 6	9 🛛 3B
(-)	qualification. Radiation Lot Acceptance Testing is available -	GND 🛛 7	8 🛛 3A

contact factory for details.

DESCRIPTION

The <u>'AC02</u> devices contain four independent 2-input NOR gates that perform the Boolean function $Y = \overline{A} \cdot \overline{B}$ or $Y = \overline{A + B}$ in positive logic.

ORDERING INFORMATION⁽¹⁾

T _A	PACK	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
–55°C to 125°C	J - package	tubo	5962-8761203VCA	5962-8761203VCA
	W - package	tube	5962-8761203VDA	5962-8761203VDA

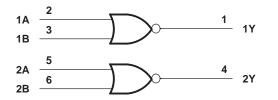
(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI Web site at www.ti.com.

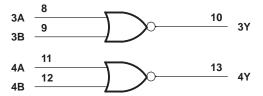
(2)Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE (EACH GATE)

INP	INPUTS						
Α	В	Y					
Н	Х	L					
Х	Н	L					
L	L	Н					

LOGIC DIAGRAM (POSITIVE LOGIC)





A

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

SCHS368A-OCTOBER 2008-REVISED DECEMBER 2008



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ABSOLUTE MAXIMUM RATINGS⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V _{CC}	Supply voltage range		-0.5	6	V
I _{IK}	Input clamp current ⁽²⁾	$V_{I} < 0 \text{ or } V_{I} > V_{CC}$		±20	mA
I _{OK}	Output clamp current ⁽²⁾	V _O < 0		±50	mA
Ι _Ο	Continuous output current	$V_{O} = 0$ to V_{CC}		±50	mA
	Continuous current through V_{CC} or GND			±100	mA
T _{stg}	Storage temperature range		-65	150	= C

(1) Stresses beyond those listed under absolute maximum ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under recommended operating conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input and output voltage ratings may be exceeded provided the input and output current ratings are observed.

RECOMMENDED OPERATING CONDITIONS⁽¹⁾

			T _A = 2	5°C	-55°C TO 125°C MIN MAX		UNIT
			MIN	MAX			
V_{CC}	Supply voltage		1.5	5.5	1.5	5.5	V
		V _{CC} = 1.5 V	1.2		1.2		
VIH	High-level input voltage	V _{CC} = 3 V	2.1		2.1		V
		V _{CC} = 5.5 V	3.85		3.85		
	Low-level input voltage	V _{CC} = 1.5 V		0.3		0.3	
VIL		$V_{CC} = 3 V$		0.9		0.9	V
		V _{CC} = 5.5 V		1.65		1.65	
VI	Input voltage		0	V_{CC}	0	V_{CC}	V
Vo	Output voltage		0	V _{CC}	0	V _{CC}	V
I _{OH}	High-level output current	$V_{CC} = 4.5 V \text{ to } 5.5 V$		-24		-24	mA
I _{OL}	Low-level output current	$V_{CC} = 4.5 V \text{ to } 5.5 V$		24		24	mA
A+/A.	Input transition rise or fall rate	V_{CC} = 1.5 V to 3 V		50		50	n 0//
Δι/ΔV	Input transition rise or fall rate	$V_{CC} = 3.6 \text{ V to } 5.5 \text{ V}$		20		20	ns/V

 All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

2



SCHS368A-OCTOBER 2008-REVISED DECEMBER 2008

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ELECTRICAL CHARACTERISTICS

over operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V _{cc}	T _A = 25°C		–55°C TO 125°C		UNIT
				MIN	MAX	MIN	MAX	
			1.5 V	1.4		1.4		
		I _{OH} = -50 μA	3 V	2.9		2.9		
N/			4.5 V	4.4		4.4		V
V _{OH}	$V_{I} = V_{IH} \text{ or } V_{IL}$	$I_{OH} = -4mA$	3 V	2.58		2.4		v
		I _{OH} = -24 mA	4.5 V	3.94		3.7		
		$I_{OH} = -50 \text{ mA}^{(1)}$	5.5 V			3.85		
			1.5 V		0.1		0.1	
		I _{OL} = 50 μA	3 V		0.1		0.1	
N/			4.5 V		0.1		0.1	V
V _{OL}	$V_{I} = V_{IH} \text{ or } V_{IL}$	I _{OL} = 12 mA	3 V		0.36		0.5	v
		I _{OL} = 24 mA	4.5 V		0.36		0.525	
		I _{OL} = 50 mA ⁽¹⁾	5.5 V				1.65	
I _I	$V_I = V_{CC}$ or GND	•	5.5 V		±0.1		±1	μA
I _{CC}	$V_I = V_{CC}$ or GND	, I _O = 0	5.5 V		4		80	μA
CI					10		10	pF

 Test one output at a time, not exceeding 1-second duration. Measurement is made by forcing indicated current and measuring voltage to minimize power dissipation. Test verifies a minimum 50-Ω transmission-line drive capability at 85°C and 75-Ω transmission-line drive capability at 125°C.

3

SCHS368A-OCTOBER 2008-REVISED DECEMBER 2008

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SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range, V_{CC} = 1.5 V, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	TO (OUTPUT)	–55°C TO 125°C	UNIT
	(INPUT)	(001201)	MIN MAX	
t _{PLH}	A or B	V	144	20
t _{PHL}	AUID	Ť	144	ns

SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	–55°C 125		UNIT
	(INFOT)	(601-01)	MIN	MAX	
t _{PLH}	A or B	v	4	16.1	20
t _{PHL}	AOIB	ľ	4	16.1	ns

SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range, $V_{CC} = 5 V \pm 0.5 V$, $C_L = 50 pF$ (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	–55°C 125		UNIT
	(INFOT)	(001-01)	MIN	MAX	
t _{PLH}	A or B	V	2.9	11.5	
t _{PHL}	AOIB	Ť	2.9	11.5	ns

OPERATING CHARACTERISTICS

 $V_{CC} = 5 \text{ V}, \text{ T}_{A} = 25^{\circ}\text{C}$

	PARAMETER	TYP	UNIT
C _{pd}	Power dissipation capacitance	55	pF

4

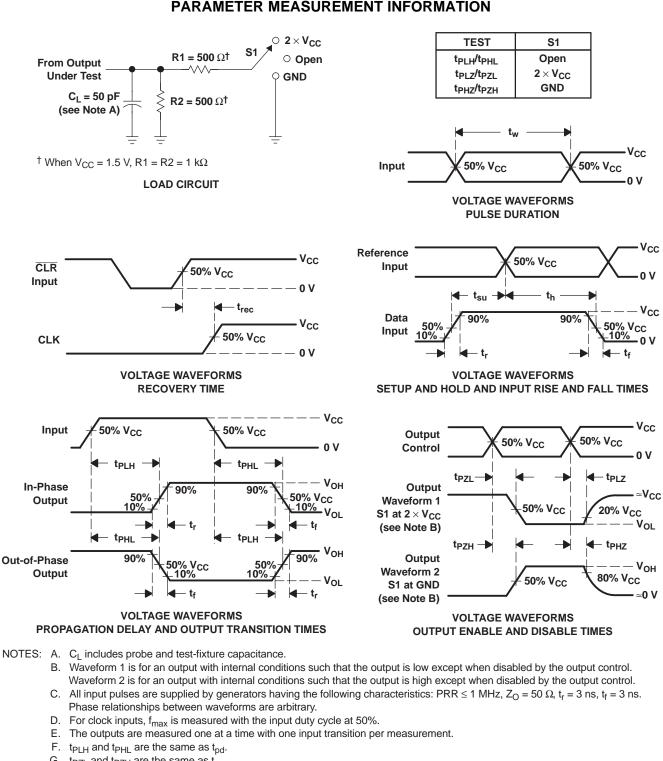
SN54AC02-SP





EXAS

INSTRUMENTS



- G. t_{PZL} and t_{PZH} are the same as t_{en} .
- H. t_{PLZ} and t_{PHZ} are the same as t_{dis} .

Figure 1. Load Circuit and Voltage Waveforms



PACKAGING INFORMATION

Orderable Device	Status	Package Type		Pins	-	Eco Plan	Lead finish/	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	Ball material	(3)		(4/5)	
							(6)				
5962-8761203VCA	ACTIVE	CDIP	J	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8761203VC A SNV54AC02J	Samples
5962-8761203VDA	ACTIVE	CFP	W	14	25	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8761203VD A SNV54AC02W	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54AC02-SP :

• Catalog : SN54AC02-DIE

NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

TEXAS INSTRUMENTS

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5-Dec-2023

TUBE



- B - Alignment groove width

*All dimensions are nominal

Device	Package Name	Package Name Package Type Pins SPQ L		L (mm)	W (mm)	Τ (μm)	B (mm)	
5962-8761203VDA	W	CFP	14	25	506.98	26.16	6220	NA

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F14



GENERIC PACKAGE VIEW

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



J0014A



PACKAGE OUTLINE

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE



NOTES:

- 1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.
- 3. This package is hermitically sealed with a ceramic lid using glass frit.
- Index point is provided on cap for terminal identification only and on press ceramic glass frit seal only.
 Falls within MIL-STD-1835 and GDIP1-T14.



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EXAMPLE BOARD LAYOUT

CDIP - 5.08 mm max height

CERAMIC DUAL IN LINE PACKAGE





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